

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-59. (Canceled)

60. (Currently Amended) A method of manufacturing a wiring substrate, comprising:

disposing a first droplet of a first plurality of droplets over a substrate by a first inkjet head, the first droplet including and second droplets over a substrate, the first and second droplets not being in contact with each other, each of the first and second droplets including a first solvent component and a first functional particle;

irradiating the first droplet with a first laser beam by a first semiconductor laser which is attached to the first inkjet head, the first droplet being partially gasified;

disposing a second droplet of the first plurality of droplets over the substrate by the first inkjet head, the second droplet being separated to the first droplet in a first distance;

irradiating the second droplet with a second laser beam by the first semiconductor laser, the second droplet being partially gasified;

gasifying a first part of the first solvent component from each of the first and second droplets by irradiating the first and second droplets with a first light to form first and second applied films over the substrate, the first and second applied films not being in contact with each other, each of the first and second applied films including a second part of the first solvent component and the first functional particle;

disposing a third droplet of a second plurality of droplets over the substrate by a second inkjet head between the first and second applied films, the third droplet contacting at least one of the first and second applied films, the third droplet being positioned between

the first droplet and the second droplet, the third droplet contacting the first and second droplets; including a second solvent component and a second functional particle;

irradiating the third droplet with a third laser beam by a second semiconductor laser which is attached to the second inkjet head, the third droplet being partially gasified; and
sintering the first, second and third droplets by irradiating the first, second and third films with a light to form a wiring over the substrate.

~~gasifying a first part of the second solvent component from the third droplet by irradiating the third droplet with the first light to form a third applied film between the first and second applied films, the third applied film contacting at least one of the first and second applied films, the third applied film including a second part of the second solvent component and the second functional particle; and~~

~~excluding the second part of the first solvent component and the second part of the second solvent component from the first, second and third applied films by sintering the first, second and third applied films to form a functional material.~~

61. (Currently Amended) The method of manufacturing a wiring substrate according to claim 60, an intensity of the light being higher than that of the first, second and third laser beams.~~the process of sintering the first, second, and third applied films including irradiating the first, second, and third applied films with a second light, an intensity of the second light being higher than that of the first light.~~

62. (Currently Amended) The method of manufacturing a wiring substrate according to claim 60, the first functional particle being coated by a coating film during the process of disposing of the first droplet.~~each of the first and second applied films including a coating film that coats the first functional particle;~~ the coating film being removed ~~at~~ during the process of sintering the first, second, and third applied films.

63-65. (Canceled)

66. (Currently Amended) The method of manufacturing a wiring substrate according to claim 60, the first ~~light~~ laser beam being beamed to the first droplet ~~and the second droplets~~ through a diffraction optical element.

67. (Currently Amended) The method of manufacturing a wiring substrate according to claim 60, the first ~~light~~ laser beam being reflected by a reflector before the first light is beamed to the first droplet ~~and second droplets~~.

68. (Currently Amended) The method of manufacturing a wiring substrate according to claim 60, the substrate ~~being~~ is made of a transparent material, ~~the first light passing from a second surface of the substrate to a first surface of the substrate, the first and the second droplets being disposed over the first surface of the substrate.~~

69. (Currently Amended) The method of manufacturing a wiring substrate according to claim 60, a viscosity of the first droplet during the process of disposing of the first droplet being lower than that of the first droplet during the process of disposing of the second droplet ~~being lower than that of the first applied film.~~

70. (Previously Presented) The method for manufacturing a wiring substrate according to claim 60, each of the first and second droplets including a photothermal conversion material that has an absorption band in the wavelength region of the first light.

71. (Currently Amended) A method of manufacturing a wiring substrate, comprising:

disposing a first droplet of a first plurality of droplets over a substrate by a first inkjet head, the first droplet including a first functional particle ~~over a substrate, the first droplet including a first solvent component and a first functional particle;~~

disposing a second droplet of the first plurality of droplets over the substrate by the first inkjet head, the second droplet being separated from the first droplet by a first distance;

irradiating the first droplet with a first laser beam by a first semiconductor laser which is attached to the first inkjet head, the first droplet being partially gasified;

irradiating the second droplet with a second laser beam by the first semiconductor laser, the second droplet being partially gasified;

disposing a third droplet of a second plurality of droplets over the substrate by a second inkjet head, the third droplet being positioned between the first droplet and the second droplet, the third droplet contacting the first and the second droplets;

irradiating the third droplet with a third laser beam by a second semiconductor laser which is attached to the second inkjet head, the third droplet being partially gasified; and

sintering the first, second and third droplets by irradiating the first, second and third films with a light to form a wiring over the substrate.

~~gasifying a first part of the first solvent component from the first droplet by irradiating the first droplet with a first light to form a first applied film over the substrate, the first applied film including a second part of the first solvent component and the first functional particle;~~

~~disposing a second droplet over the substrate, the second droplet contacting at least a part of the first applied film, the second droplet including a second solvent component and a second functional particle;~~

~~gasifying a first part of the second solvent component from the second droplet by irradiating the second droplet with the first light to form a second applied film over the substrate, the second applied film contacting at least a part of the first applied film, the second applied film including a second part of the second solvent component and the second functional particle;~~

~~_____excluding the second part of the first solvent component and the second part of the second solvent component from the first and second applied films by sintering the first and second applied films to form a functional material.~~

72. (Currently Amended) The method of manufacturing a wiring substrate according to claim 71, ~~the process of sintering the first and second applied films including irradiating the first and second applied films with a second light, an intensity of the second light being higher than that of the first, second and third laser beams.~~ light.

73-74. (Canceled)

75. (New) A method of manufacturing a wiring substrate, comprising;

discharging a plurality of first droplets over a substrate by a first inkjet head, each of the plurality of first droplets being disposed in line, not contacting to each other;

irradiating the plurality of first droplets with a first laser beam by a first semiconductor laser that is attached to the first inkjet head, each of the plurality of first droplets being partially gasified by the irradiation of the first laser beam;

discharging a plurality of second droplets over the substrate by a second inkjet head, each of the plurality of second droplets being separately disposed between the plurality of droplets; and

irradiating the plurality of second droplets with a second laser beam by a second semiconductor laser that is attached to the second inkjet head, each of the plurality of second droplets being partially gasified by the irradiation of the second laser beam.